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<b>Title</b>	<i>Reference Design Report for a 10 W CV/ CC USB Charger using InnoSwitch™-CH INN2023K</i>
<b>Specification</b>	85 VAC – 264 VAC Input; 5 V, 2 A Output (end of USB Cable)
<b>Application</b>	Cell Phone / USB Charger
<b>Author</b>	Applications Engineering Department
<b>Document Number</b>	RDR-420
<b>Date</b>	April 20, 2015
<b>Revision</b>	1.1

### **Summary and Features**

- InnoSwitch-CH - Industry first AC/DC ICs with isolated, safety rated integrated feedback
- All the benefits of secondary side control with the simplicity of primary side regulation
  - $\pm 3\%$  CV,  $\pm 5\%$  CC regulation
  - Insensitive to transformer variation
  - Transient response independent of load timing
  - Smaller, lower cost output capacitors
  - $< 10$  mW no-load input power
  - Cable voltage drop compensation
- Built in synchronous rectification for high efficiency

#### PATENT INFORMATION

The products and applications illustrated herein (including transformer construction and circuits external to the products) may be covered by one or more U.S. and foreign patents, or potentially by pending U.S. and foreign patent applications assigned to Power Integrations. A complete list of Power Integrations' patents may be found at [www.powerint.com](http://www.powerint.com). Power Integrations grants its customers a license under certain patent rights as set forth at <http://www.powerint.com/ip.htm>.

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**Important Note:**

Although this board is designed to satisfy safety isolation requirements, the engineering prototype has not been agency approved. Therefore, all testing should be performed using an isolation transformer to provide the AC input to the prototype board.



## 1 Introduction

This document is an engineering report describing a 2 A, 5.0 V USB charger utilizing a device from the InnoSwitch-CH family of ICs. This design is intended to show the high power density and efficiency that is possible due to the high level of integration while still providing exceptional performance.

This document contains the power supply specification, schematic, bill of materials, transformer documentation, printed circuit layout, and performance data.

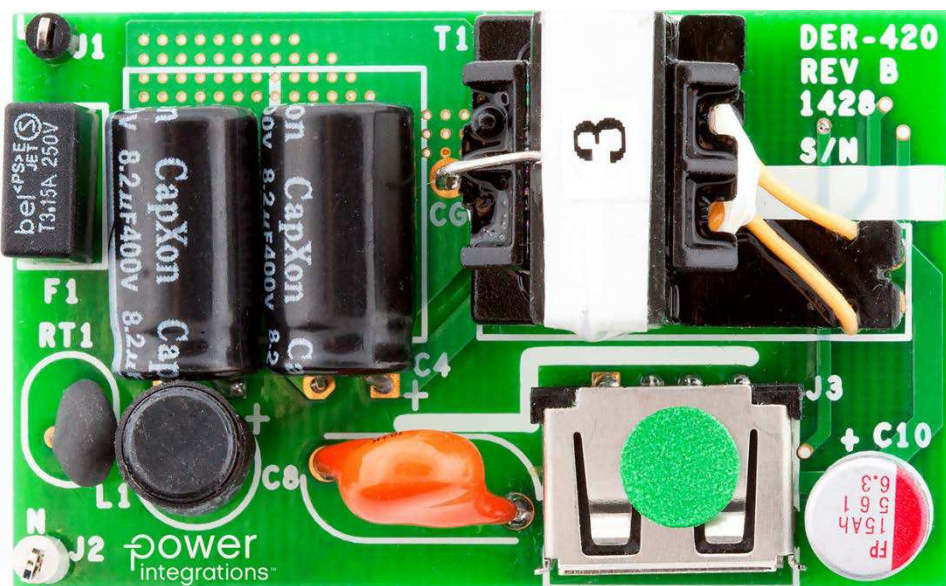


Figure 1 – Populated Circuit Board Photograph, Top.

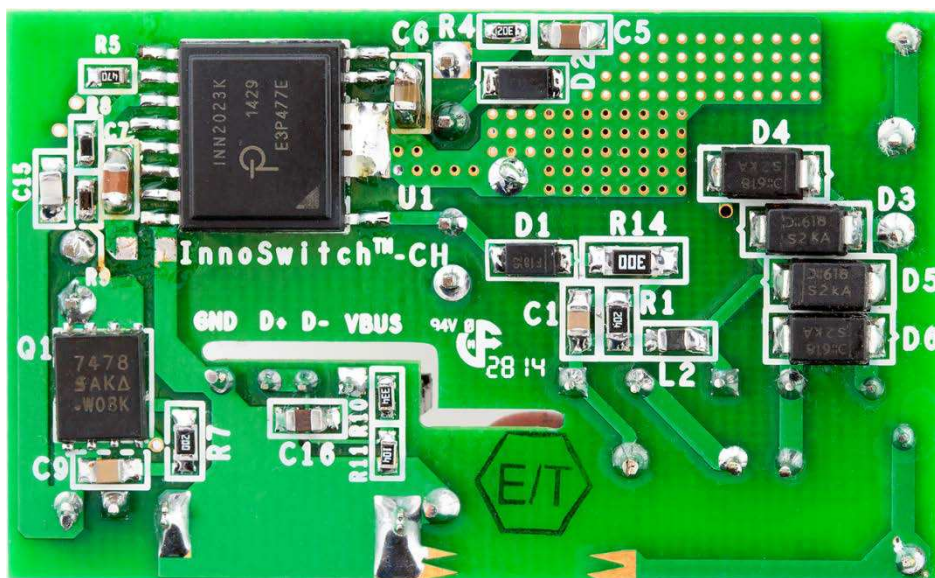


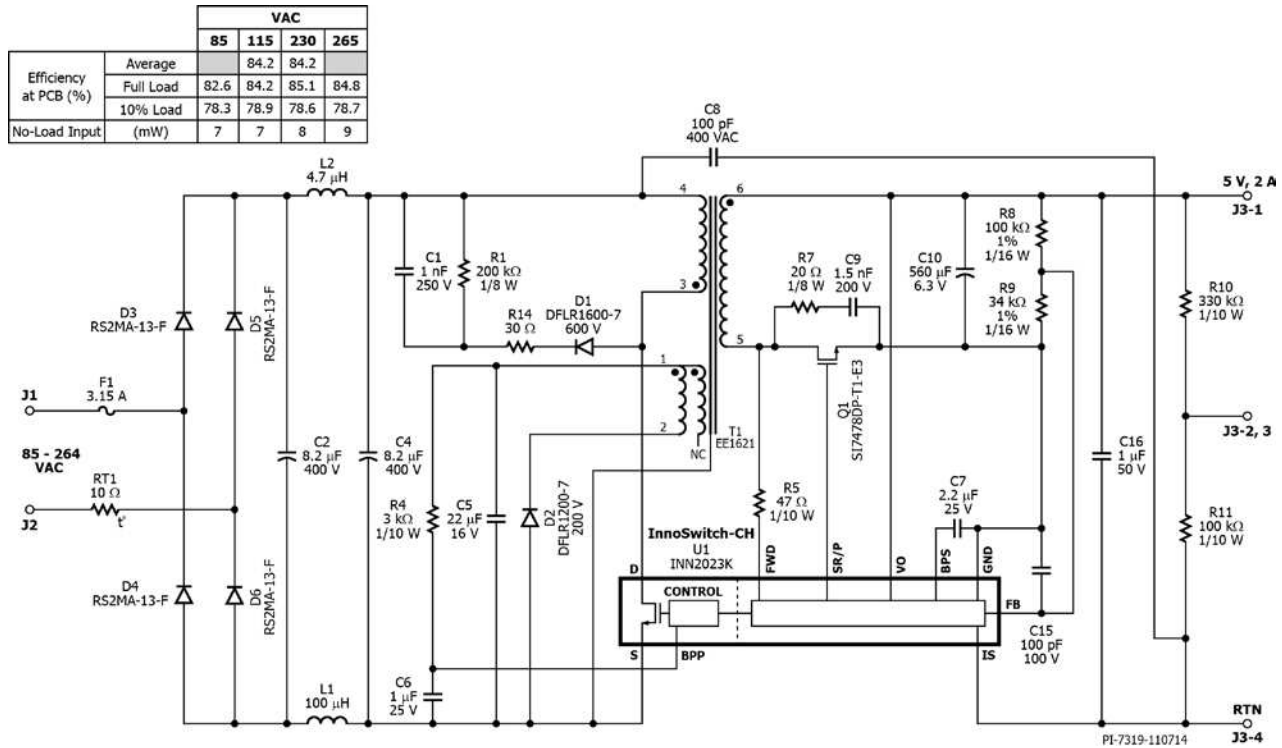
Figure 2 – Populated Circuit Board Photograph, Bottom.

## 2 Power Supply Specification

The table below represents the minimum acceptable performance of the design. Actual performance is listed in the results section.

Description	Symbol	Min	Typ	Max	Units	Comment
<b>Input</b>						
Voltage	$V_{IN}$	85		265	VAC	2 Wire – no P.E.
Frequency	$f_{LINE}$	50	50/60	64	Hz	
No-load Input Power				10	mW	230 VAC
<b>Output</b>						
Output Voltage	$V_{OUT}$	4.75	5.0	5.25	V	0.35 V cable resistance drop
Transient Output Voltage	$V_{OUT(T)}$	4.2		5.5	V	0 A - 2 A - 0 A load step end of cable
Output Ripple Voltage	$V_{RIPPLE}$			150	mV	At the end of the output cable
Output Cable Compensation	$V_{CBL}$	250	300	350	mV	At 2 A output current
Output Current CC point	$I_{OUT}$	2		2.5	A	
Auto-Restart Voltage	$V_{AR}$	2		3.5	V	At end of cable
Turn on Rise Time	$t_R$			20	ms	
Rated Output Power	$P_{OUT}$		10		W	
<b>Efficiency</b>						
Average	$\eta_{AVE[BRD]}$	84			%	Measured at USB socket
25%, 50%, 75%, and 100%	$\eta_{AVE[CBL]}$	80			%	With 0.38 V cable resistance drop
10%	$\eta_{10\%}$	79			%	
<b>Environmental</b>						
Output Cable Impedance	$R_{CBL}$		190		m $\Omega$	
Conducted EMI						Resistive load, 6 dB Margin
Safety						6 dB Margin
Audible noise				25	dB	Designed to meet
Line Surge						Measured at 3 cm
Common mode (L1/L2-PE)				6	kV	Ring Wave, Common Mode: 12 $\Omega$
ESD		$\pm 16.5$ $\pm 8$			kV kV	Contact Air discharge
Ambient Temperature	$T_{AMB}$	0		40	$^{\circ}\text{C}$	No degradation in performance Free convection, sea level in sealed enclosure

### 3 Schematic



## 4 Circuit Description

### 4.1 Input EMI Filtering

Fuse F1 provides protection against catastrophic failure of components on the primary side.

An inrush limiting thermistor (RT1) was necessary due to the low surge current rating of the rectifier diodes (D1-D4) and the relatively high value and therefore low impedance of the bulk storage capacitors C2 and C4.

Physically small diodes were selected for D1-D4 due to the limited space, specifically height from PCB to case.

Capacitor C2 and C4 provide filtering of the rectified AC input and together with L1 and L2 form a  $\pi$  (pi) filter to attenuate differential mode EMI. A low value Y capacitor (C8) reduces common mode EMI.

### 4.1 InnoSwitch-CH IC Primary

One side of the transformer primary is connected to the rectified DC bus, the other is connected to the integrated 650 V power MOSFET inside the InnoSwitch-CH IC (U1).

A low cost RCD clamp formed by D1, R1, R14 and C1 limits the peak drain voltage due to the effects of transformer and output trace inductance.

The IC is self-starting, using an internal high voltage current source to charge the BPP pin capacitor (C6) when AC is first applied. During normal operation the primary side block is powered from an auxiliary winding on the transformer. The output of this is configured as a flyback winding, rectified and filtered (D2 and C5) and fed in the BPP pin via a current limiting resistor R4.

Output regulation is achieved using On/Off control, the number of enabled switching cycles are adjusted based on the output load. At high load most switching cycles are enabled, and at light load or no-load most cycled are disabled or skipped. Once a cycle is enabled, the power MOSFET remain on until the primary current ramps to the device current limit for the specific operating state. There are four operating states (current limits) arrange such that the frequency content of the primary current switching pattern remains out of the audible range until at light load where the transformer flux density and therefore audible noise generation is at a very low level.



## 4.2 *InnoSwitch-CH IC Secondary*

The secondary side of the InnoSwitch-CH provides output voltage, output current sensing and drive to a MOSFET providing synchronous rectification.

The secondary of the transformer is rectified by Q1 and filtered by C10. High frequency ringing during switching transients that would otherwise create high voltage across Q1 and radiated EMI is reduced via snubber components R7 and C9.

To reduce dissipation synchronous rectification (SR) is provided by Q1. The gate of Q1 is turned on based on the winding voltage sensed via R5 and the FWD pin of the IC. In continuous conduction mode operation the power MOSFET is turned off just prior to the secondary side commanding a new switching cycle from the primary. In discontinuous mode the MOSFET is turned off when the voltage drop across the MOSFET falls below a threshold. Secondary side control of the primary side MOSFET ensure that it is never on simultaneously with the synchronous rectification MOSFET. The MOSFET drive signal is output on the SR/P pin.

The secondary side of the IC is self-powered from either the secondary winding forward voltage or the output voltage. During CV operation the output voltage powers the device, fed into the VO pin.

During CC operation, when the output voltage falls the device will power itself from the secondary winding directly. During the on-time of the primary side MOSFET the forward voltage that appears across the secondary winding is used to charge the decoupling capacitor C7 via R5 and an internal regulator. The unit enters auto-restart when the sensed output voltage is lower than 3 V.

Output current is sensed internally between the IS and GND pins with a threshold of 35 mV to minimize losses. Once the internal current sense threshold is exceeded, the device adjusts the number of enabled switching cycles to maintain a fixed output current.

Below the CC threshold the device operates in constant voltage mode. The output voltage is sensed via resistor divider R8 and R9 operation with a reference voltage of 1.265 V on the FB pin when at the regulation output voltage.



### 5 PCB Layout

PCB copper thickness is 2 oz (2.8 mils / 70 µm) unless otherwise stated

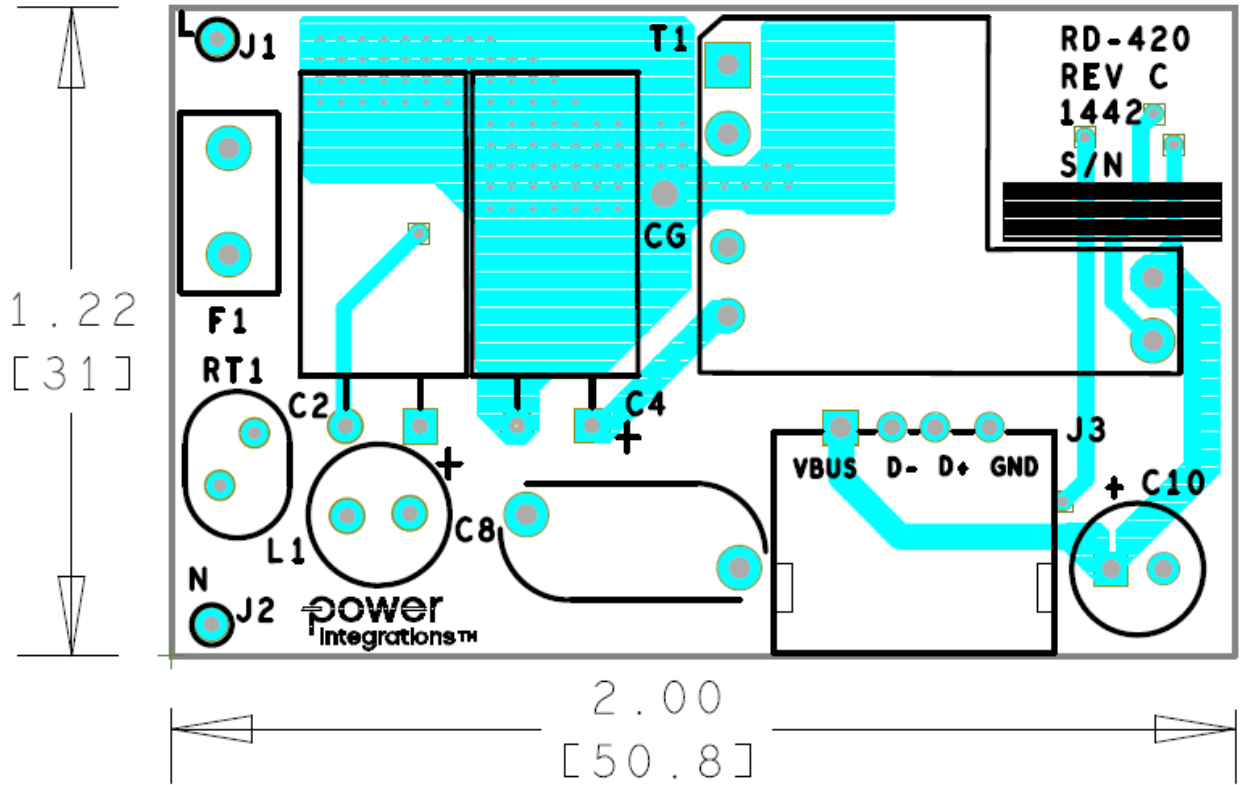


Figure 4 – Printed Circuit Layout, Top.



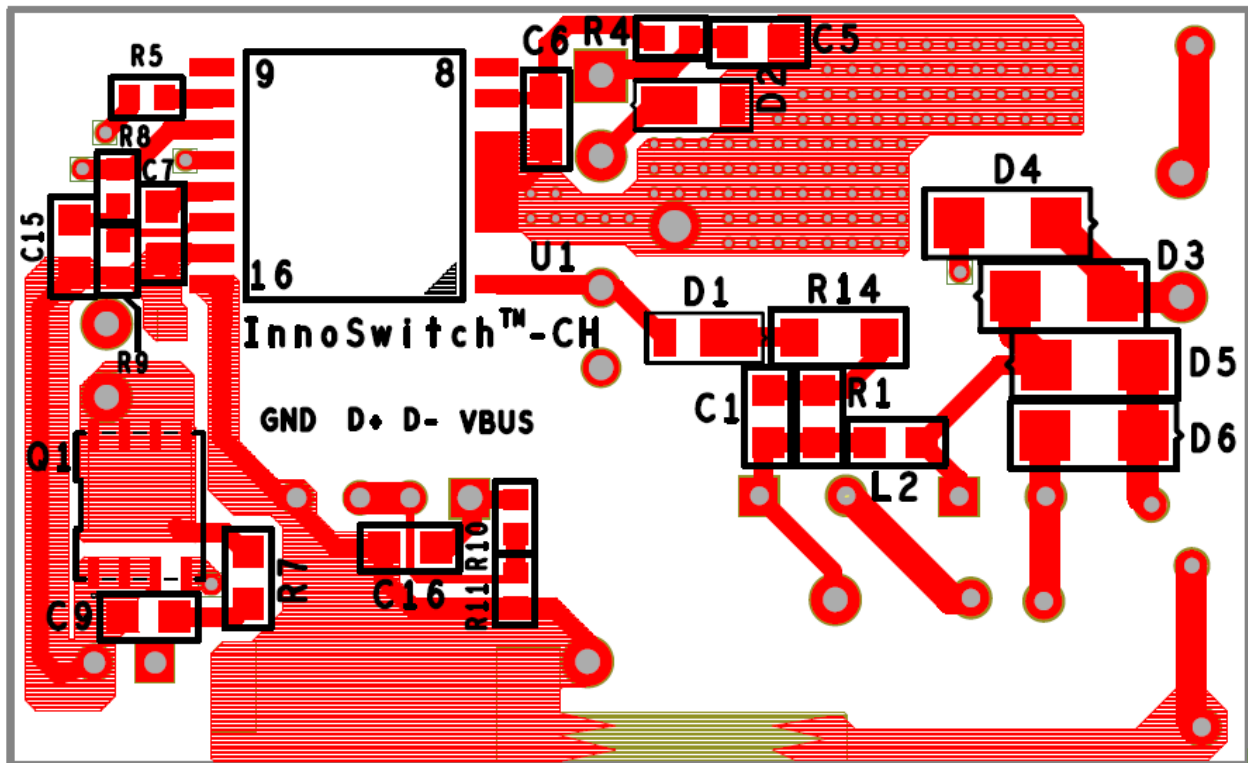


Figure 5 – Printed Circuit Layout, Bottom.

## 6 Bill of Materials

Item	Qty	Ref Des	Description	Mfg Part Number	Mfg
1	1	C1	1 nF, 250 V, Ceramic, X7R, 0805	GRM21AR72E102KW01D	Murata
2	2	C2 C4	8.2 $\mu$ F, 400 V, Electrolytic, (8 x 14) 8.2 $\mu$ F, 400 V, Electrolytic, (8 x 14), Alternate part	400AX8.2M8X16	Capxon Rubycon
3	1	C5	22 $\mu$ F, 16 V, Ceramic, X5R, 0805	C2012X5R1C226K	TDK
4	1	C6	1 $\mu$ F, 25 V, Ceramic, X5R, 0805	C2012X5R1E105K	TDK
5	1	C7	2.2 $\mu$ F, 25 V, Ceramic, X7R, 0805	C2012X7R1E225M	TDK
6	1	C8	100 pF, Ceramic, Y1	440LT10-R	Vishay
7	1	C9	1.5 nF, 200 V, 10%, Ceramic, X7R, 0805	08052C152KAT2A	AVX
8	1	C10	560 $\mu$ F, 6.3 V, Al Organic Polymer, Gen. Purpose, 20%	RS80J561MDN1JT	Nichicon
9	1	C15	100 pF 100 V 10 % X7R 0805	08051C101JAT2A	AVX
10	1	C16	1 $\mu$ F, 50 V, Ceramic, X5R, 0805	08055D105KAT2A	AVX
11	1	D1	600 V, 1 A, Rectifier, Glass Passivated, POWERDI 123	DFLR1600-7	Diodes, Inc.
12	1	D2	200 V, 1 A, Rectifier, Glass Passivated, POWERDI 123	DFLR1200-7	Diodes, Inc.
13	4	D3 D4 D5 D6	800 V, 1.5 A, Gen Purpose, SMA 800 V, 1.5 A, Gen Purpose, SMA, Alternate part	S2KA-13-F RS2MA-13-F	Diodes, Inc. Diodes, Inc.
14	1	F1	3.15 A, 250 V, Slow, RST	507-1181	Belfuse
15	1	J1	Test Point, BLK, Miniature THRU-HOLE MOUNT	5001K-ND	Keystone
16	1	J2	Test Point, WHT, Miniature THRU-HOLE MOUNT	5002K-ND	Keystone
17	1	J3	Connector USB Female Type A	USB-AF-DIP-094-H	GOLDCONN
18	1	L1	100 $\mu$ H, 0.490 A, 20%	RL-5480-2-100	Renco
19	1	L2	4.7 $\mu$ H, 600 mA SMD INDUCTOR, MULTILAYER	MLZ2012N4R7LT000	TDK
20	1	Q1	60 V, 15 A, N-Channel, PowerPAK SO-8	SI7478DP-T1-E3	Vishay
21	1	R1	200 k $\Omega$ , 5%, 1/8 W, Thick Film, 0805	ERJ-6GEYJ204V	Panasonic
22	1	R4	3 k $\Omega$ , 5%, 1/10 W, Thick Film, 0603	ERJ-3GEYJ302V	Panasonic
23	1	R5	47 $\Omega$ , 5%, 1/10 W, Thick Film, 0603	ERJ-3GEYJ470V	Panasonic
24	1	R7	20 $\Omega$ , 5%, 1/8 W, Thick Film, 0805	ERJ-6GEYJ200V	Panasonic
25	1	R8	100 k $\Omega$ , 1%, 1/16 W, Thick Film, 0603	ERJ-3EKF1003V	Panasonic
26	1	R9	34 k $\Omega$ , 1%, 1/16 W, Thick Film, 0603	ERJ-3EKF3402V	Panasonic
27	1	R10	330 k $\Omega$ , 5%, 1/10 W, Thick Film, 0603	ERJ-3GEYJ334V	Panasonic
28	1	R11	100 k $\Omega$ , 5%, 1/10 W, Thick Film, 0603	ERJ-3GEYJ104V	Panasonic
29	1	R14	30 $\Omega$ , 5%, 1/4 W, Thick Film, 1206	ERJ-8GEYJ300V	Panasonic
30	1	RT1	NTC Thermistor, 10 Ohms, 0.7 A	MF72-010D5	Cantherm
31	1	T1	Custom (see transformer section for material set)	SNX-R1776 TSD-3517	Santronics Premier Magnetics
32	1	U1	InnoSwitch-CH IC eSOP-R16B	INN2023K	Power Integrations

## 7 Transformer Specification

### 7.1 Electrical Diagram

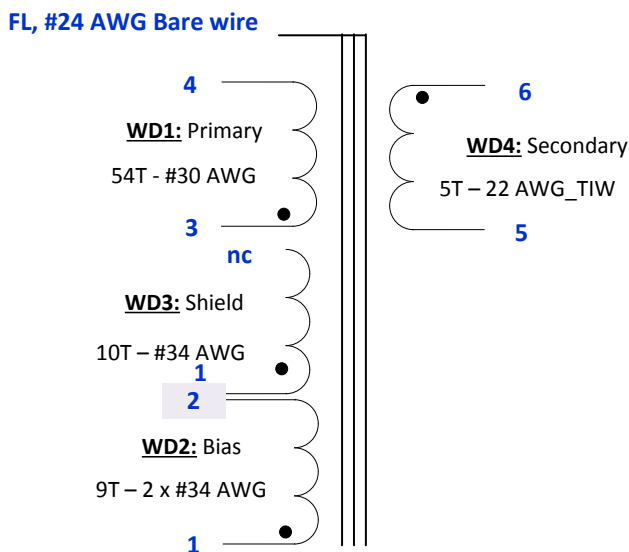


Figure 6 – Transformer Electrical Diagram.

### 7.2 Electrical Specifications

<b>Primary Inductance</b>	Pins 3-4, all other windings open, measured at 100 kHz, 0.4 V <sub>RMS</sub> .	546 μH ± 5%
<b>Resonant Frequency</b>	Pins 3-4, all other windings open.	1200 kHz (min)
<b>Primary Leakage Inductance</b>	Pins 3-4, with pins 5-6 shorted, measured at 100 kHz, 0.4 V <sub>RMS</sub> .	25 μH (max)

### 7.3 Materials

Item	Description
[1]	Core: EE1621; PC-40 or equivalent.
[2]	Bobbin: EE1621-Vertical – 8 pins (4/4) Shen Zhen Xin Yu Jia Technology Ltd.
[3]	Magnet Wire: # 30 AWG, double coated.
[4]	Magnet Wire: # 34 AWG, double coated.
[5]	Magnet Wire: # 22 AWG, Triple Insulated Wire.
[6]	Tape: 3M 1298 Polyester Film, 2 mil thick, 5.5 mm wide.
[7]	Epoxy: Devcon, 5 Minute Epoxy, No. 14210; or equivalent.
[8]	Bus wire: # 24 AWG, Belden Electronics Div; or equivalent.
[9]	Varnish: Dolph BC-359.

## 7.4 Transformer Build Diagram

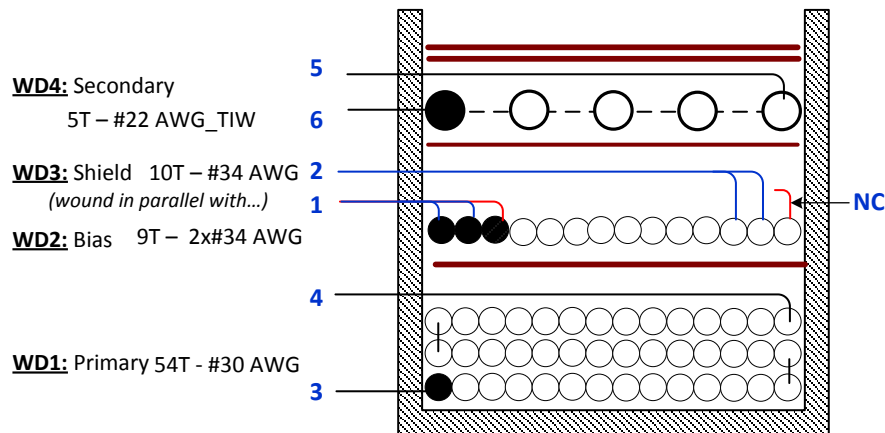
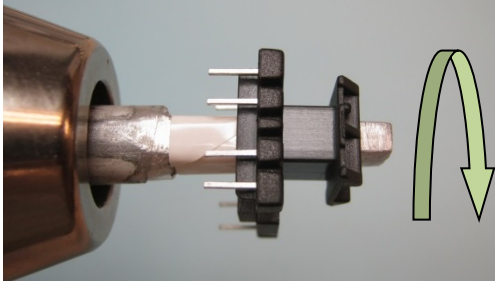
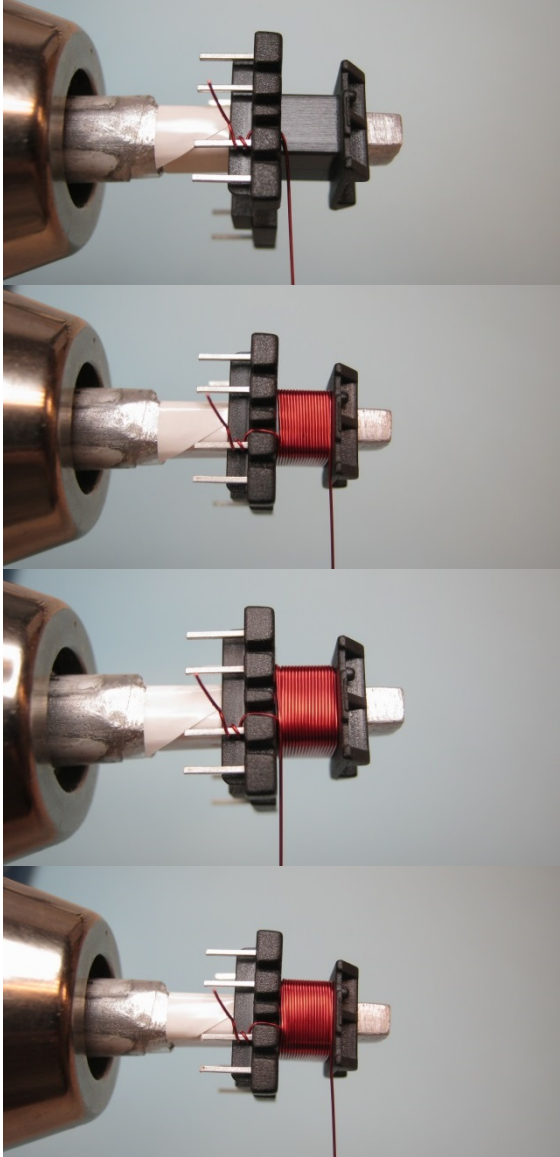


Figure 7 – Transformer Build Diagram.

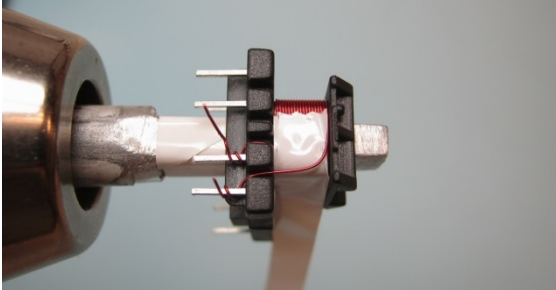
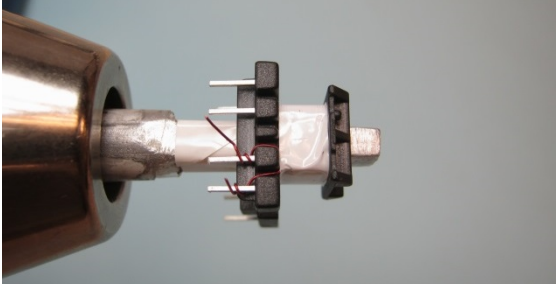
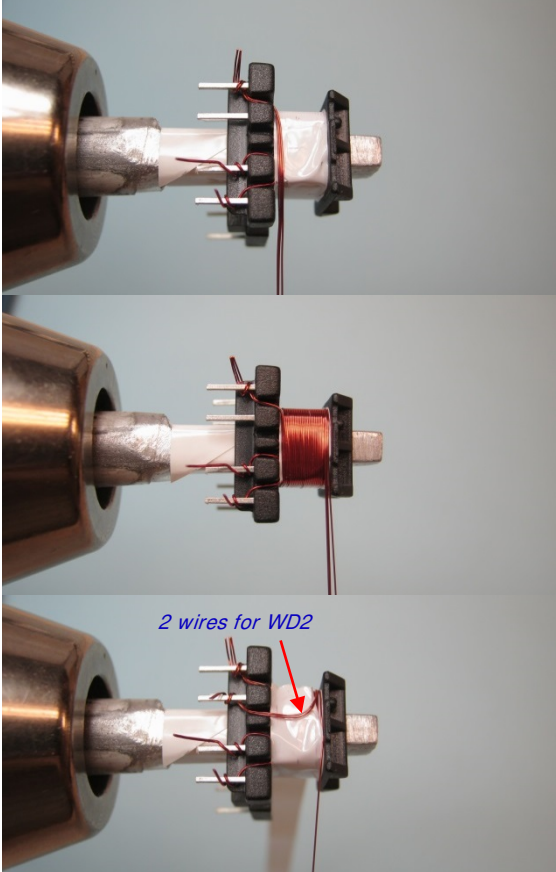
## 7.5 Transformer Instructions

<b>Winding Preparation</b>	For the purpose of these instructions, bobbin is oriented on winder such that pin side is on the left side. Winding direction is clockwise direction.
<b>WD1 Primary</b>	Start at pin 3, wind 54 turns wire item [2] in 3 layers (18T/layer) with tight tension. At the last turn bring the wire back to the left and finish at pin 4.
<b>Insulation</b>	1 layer of tape [6] for insulation.
<b>WD2 &amp; WD3 Bias &amp; Shield</b>	Use 3 wires item [4], start at pin 1, and wind 9 turns from left to right. At the last turn, bring 2 wires to the left to terminate at pin 2 for WD2. Then continue winding on the 3 <sup>rd</sup> wire 1 more turn and left no-connect for WD3.
<b>Insulation</b>	1 layer of tape [6] for insulation.
<b>WD4 Secondary</b>	Start at pin 6, wind 5 turns wire item [5], spread wire evenly. At the last turn bring the wire back to the left and finish at pin 5.
<b>Insulation</b>	2 Layer of tape [6] to secure the windings.
<b>Finish</b>	Gap core halves for 546 $\mu$ H inductance. Place epoxy item [7] onto both center legs of core halves, (see illustration below). Wrap core halves and bus wire item [8] with tape, (see illustration below). Varnish with item [9].

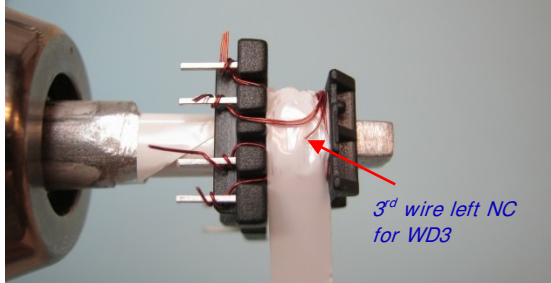
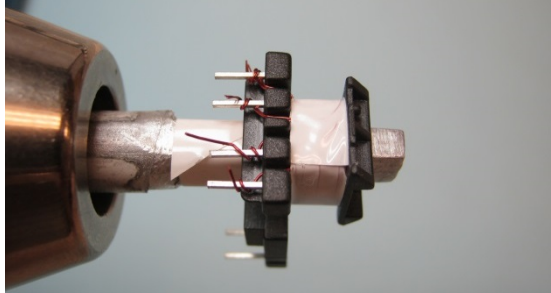
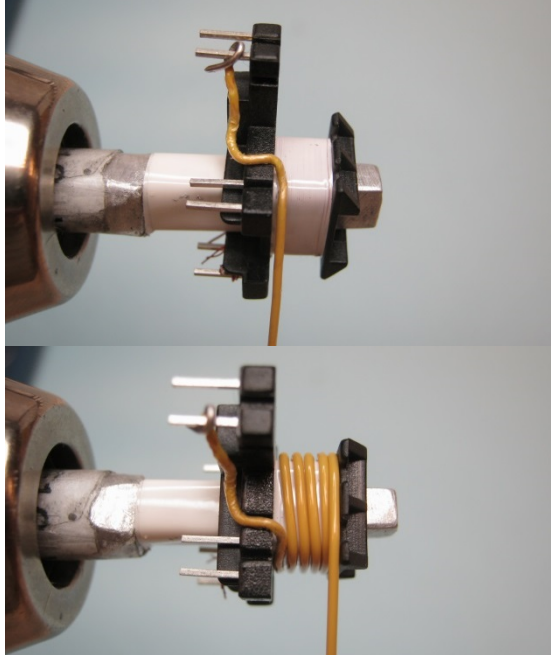
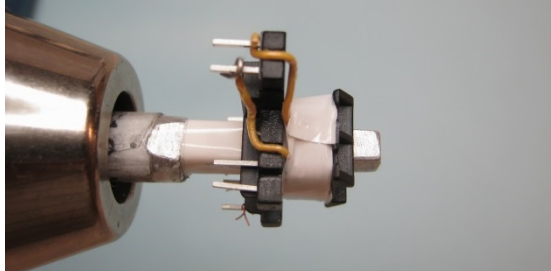
**7.6 Transformer Illustrations**

<p><b>Winding Preparation</b></p>		<p>For the purpose of these instructions, bobbin is oriented on winder such that pin side is on the left side. Winding direction is clockwise direction.</p>
<p><b>WD1 Primary</b></p>		<p>Start at pin 3, wind 54 turns wire item [2] in 3 layers (18T/layer) with tight tension. At the last turn bring the wire back to the left and finish at pin 4.</p>

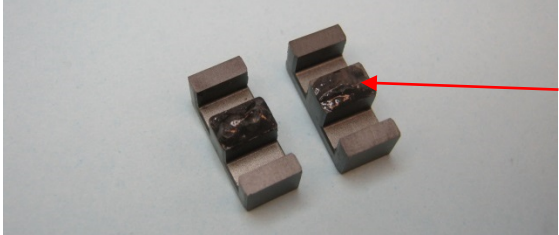
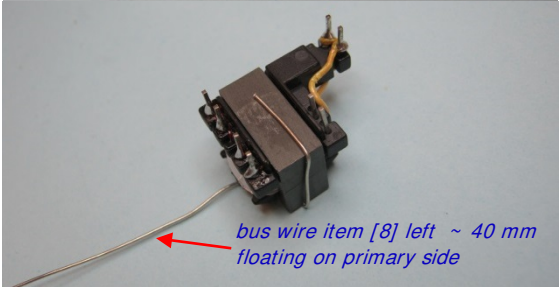
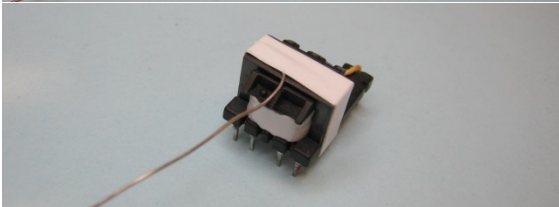


		
<p><b>Insulation</b></p>		<p>1 layer of tape [6] for insulation.</p>
<p><b>WD2 &amp; WD3 Bias &amp; Shield</b></p>		<p>Use 3 wires item [4], start at pin 1, and wind 9 turns from left to right. At the last turn, bring 2 wires to the left to terminate at pin 2 for WD2. Then continue winding on the 3<sup>rd</sup> wire 1 more turn and left no-connect for WD3.</p>



		
<p><b>Insulation</b></p>		<p>1 layer of tape [6] for insulation.</p>
<p><b>WD4 Secondary</b></p>		<p>Start at pin 6, wind 5 turns wire item [5], spread wire evenly. At the last turn bring the wire back to the left and finish at pin 5.</p>
<p><b>Insulation</b></p>		<p>2 layer of tape [6] to secure the windings.</p>



<p><b>Finish</b></p>	 <p>A photograph showing two dark-colored core halves. Each half has a small, dark, rectangular epoxy item applied to its center leg. A red arrow points from the text on the right to the epoxy on the right-hand core half.</p>	<p>Gap core halves for 546 <math>\mu</math>H inductance. Place epoxy item [7] onto both center legs of core halves, (see illustration beside).</p>
	 <p>A photograph of the core assembly with a bus wire attached. The bus wire is a thin, copper-colored wire that is connected to the primary side of the core. A red arrow points from the text below to the bus wire.</p> <p><i>bus wire item [8] left ~ 40 mm floating on primary side</i></p>	
	 <p>A photograph of the core assembly wrapped in white tape. The bus wire is still visible, and the core is now fully covered in tape.</p>	<p>Wrap core halves and bus wire item [8] with tape, (see illustration below). Varnish with item [9].</p>

## 8 Transformer Design Spreadsheet

ACDC_InnoSwitch-CH_101614; Rev.2.0; Copyright Power Integrations 2014	INPUT	INFO	OUTPUT	UNIT	ACDC_InnoSwitch_101614_Rev2-0; InnoSwitch-CH Continuous/ Discontinuous Flyback Transformer Design Spreadsheet
<b>ENTER APPLICATION VARIABLES</b>					
VACMIN			85	V	Minimum AC Input Voltage
VACMAX			265	V	Maximum AC Input Voltage
fL			50	Hz	AC Mains Frequency
VO	5.00		5.00	V	Output Voltage (continuous power at the end of the cable)
IO	2.00		2.00	A	Power Supply Output Current (corresponding to peak power)
Power			10.6	W	Continuous Output Power, including cable drop compensation
n	0.82		0.82		Efficiency Estimate at output terminals. Use 0.8 if no better data available
Z			0.50		Z Factor. Ratio of secondary side losses to the total losses in the power supply. Use 0.5 if no better data available
tC			3.00	mSeconds	Bridge Rectifier Conduction Time Estimate
CIN	16.40	Info	16.40	uFarad	!!! Input capacitor is too small. Recommended to increase CIN above 19.05 uF to ensure VMIN > 70 V
<b>ENTER InnoSwitch VARIABLES</b>					
InnoSwitch-CH	INN20x3		INN20x3		User defined InnoSwitch
Cable drop compensation	6%		6%		Select Cable Drop Compensation option
Complete Part Number			INN2023K		Final part number including package
Chose Configuration	INC		Increased Current Limit		Enter "RED" for reduced current limit (sealed adapters), "STD" for standard current limit or "INC" for increased current limit (peak or higher power applications)
ILIMITMIN			0.682	A	Minimum Current Limit
ILIMITTYP			0.75	A	Typical Current Limit
ILIMITMAX			0.818	A	Maximum Current Limit
fSmin			93000	Hz	Minimum Device Switching Frequency
I <sup>2</sup> fmin			47.25	A <sup>2</sup> kHz	Worst case I <sup>2</sup> F parameter across the temperature range
VOR	58		58	V	Reflected Output Voltage (VOR ≤ 100 V Recommended)
VDS			5.00	V	InnoSwitch on-state Drain to Source Voltage
KP			0.80		Ripple to Peak Current Ratio at Vmin, assuming ILIMITMIN, and I <sup>2</sup> FMIN (KP < 6)
KP_TRANSIENT			0.46		Worst case transient Ripple to Peak Current Ratio. Ensure KP_TRANSIENT > 0.25
<b>ENTER BIAS WINDING VARIABLES</b>					
VB			10.00	V	Bias Winding Voltage
VDB			0.70	V	Bias Winding Diode Forward Voltage Drop
NB			9.32	V	Bias Winding Number of Turns
PIVB			102.59	V	Bias winding peak reverse voltage at VACmax and assuming VB* 1.2
<b>ENTER TRANSFORMER CORE/ CONSTRUCTION VARIABLES</b>					
Core Type	Custom		Custom		Enter Transformer Core
Core	EE1621		EE1621		Enter core part number, if necessary
Bobbin			0		Enter bobbin part number, if necessary
AE	0.325		0.325	cm <sup>2</sup>	Core Effective Cross Sectional Area



LE	3.93		3.93	cm	Core Effective Path Length
AL	2800		2800	nH/T <sup>2</sup>	Ungapped Core Effective Inductance
BW	5.40		5.40	mm	Bobbin Physical Winding Width
M			0.00	mm	Safety Margin Width (Half the Primary to Secondary Creepage Distance)
L	3		3		Number of Primary Layers
NS	5		5		Number of Secondary Turns
<b>DC INPUT VOLTAGE PARAMETERS</b>					
VMIN	62	Warning	62	V	!!! Minimum DC Input Voltage < 70 Volts. Increase VACMIN or increase CIN
VMAX			375	V	Maximum DC Input Voltage
<b>CURRENT WAVEFORM SHAPE PARAMETERS</b>					
DMAX			0.50		Duty Ratio at full load, minimum primary inductance and minimum input voltage
I AVG			0.21	A	Average Primary Current
IP			0.682	A	Peak Primary Current assuming ILIMITMIN
IR			0.546	A	Primary Ripple Current assuming ILIMITMIN, and LPMIN
IRMS			0.31	A	Primary RMS Current, assuming ILIMITMIN, and LPMIN
<b>TRANSFORMER PRIMARY DESIGN PARAMETERS</b>					
LP			546	uHenry	Typical Primary Inductance. +/- 5% to ensure a minimum primary inductance of 518 uH
LP_TOLERANCE	5.0		5.0	%	Primary inductance tolerance
NP			54		Primary Winding Number of Turns
ALG			187	nH/T <sup>2</sup>	Gapped Core Effective Inductance
BM			2868	Gauss	Maximum Operating Flux Density, BM< 3000 is recommended
BAC			1147	Gauss	AC Flux Density for Core Loss Curves (0.5 X Peak to Peak)
ur			2694		Relative Permeability of Ungapped Core
LG			0.20	mm	Gap Length (Lg > 0.1 mm)
BWE			16.2	mm	Effective Bobbin Width
OD			0.30	mm	Maximum Primary Wire Diameter including insulation
INS			0.05	mm	Estimated Total Insulation Thickness (= 2 * film thickness)
DIA			0.25	mm	Bare conductor diameter
AWG			31	AWG	Primary Wire Gauge (Rounded to next smaller standard AWG value)
CM			81	Cmils	Bare conductor effective area in circular mils
CMA			259	Cmils/ Amp	Primary Winding Current Capacity (200 < CMA < 500)
<b>TRANSFORMER SECONDARY DESIGN PARAMETERS</b>					
<b>Lumped parameters</b>					
ISP			7.37	A	Peak Secondary Current, assuming ILIMITMIN
ISRMS			3.33	A	Secondary RMS Current
IRIPPLE			2.67	A	Output Capacitor RMS Ripple Current
CMS			667	Cmils	Secondary Bare Conductor minimum circular mils
AWGS			21	AWG	Secondary Wire Gauge (Rounded up to next larger standard AWG value)
<b>VOLTAGE STRESS PARAMETERS</b>					
VDRAIN			517	V	Maximum Drain Voltage Estimate
PIVS			54	V	Output Rectifier Maximum Peak Inverse Voltage, assuming the primary has a Voltage spike 40% above VMAX and VO* 1.05
<b>TRANSFORMER SECONDARY DESIGN PARAMETERS</b>					
<b>1st output</b>					
VO1			5.30	V	Main Output Voltage directly after output rectifier

IO1			2.00	A	Output DC Current
PO1			10.60	W	Output Power
VD1			0.06	V	Output Synchronous Rectification FET Forward Voltage Drop
NS1			5.00	Turns	Output Winding Number of Turns
ISRMS1			3.33	A	Output Winding RMS Current
IRIPPLE1			2.67	A	Output Capacitor RMS Ripple Current
PIVS1			54	V	Output Rectifier Maximum Peak Inverse Voltage, assuming the primary has a Voltage spike 40% above VMAX and VO* 1.05
Recommended MOSFET			QM6006		Recommended SR FET for this output
RDSON_HOT			0.027	Ohm	RDson at 100C
VRATED			60	V	Rated voltage of selected SR FET
CMS1			667	Cmils	Output Winding Bare Conductor minimum circular mils
AWGS1			21	AWG	Wire Gauge (Rounded up to next larger standard AWG value)
DIAS1			0.73	mm	Minimum Bare Conductor Diameter
ODS1			1.08	mm	Maximum Outside Diameter for Triple Insulated Wire



## 9 Performance Data

All measurements performed with external room ambient temperature and 60 Hz input for 115 VAC range and 50 Hz for 230 VAC input range.

### 9.1 Active Mode Efficiency (at USB Socket) vs. Line

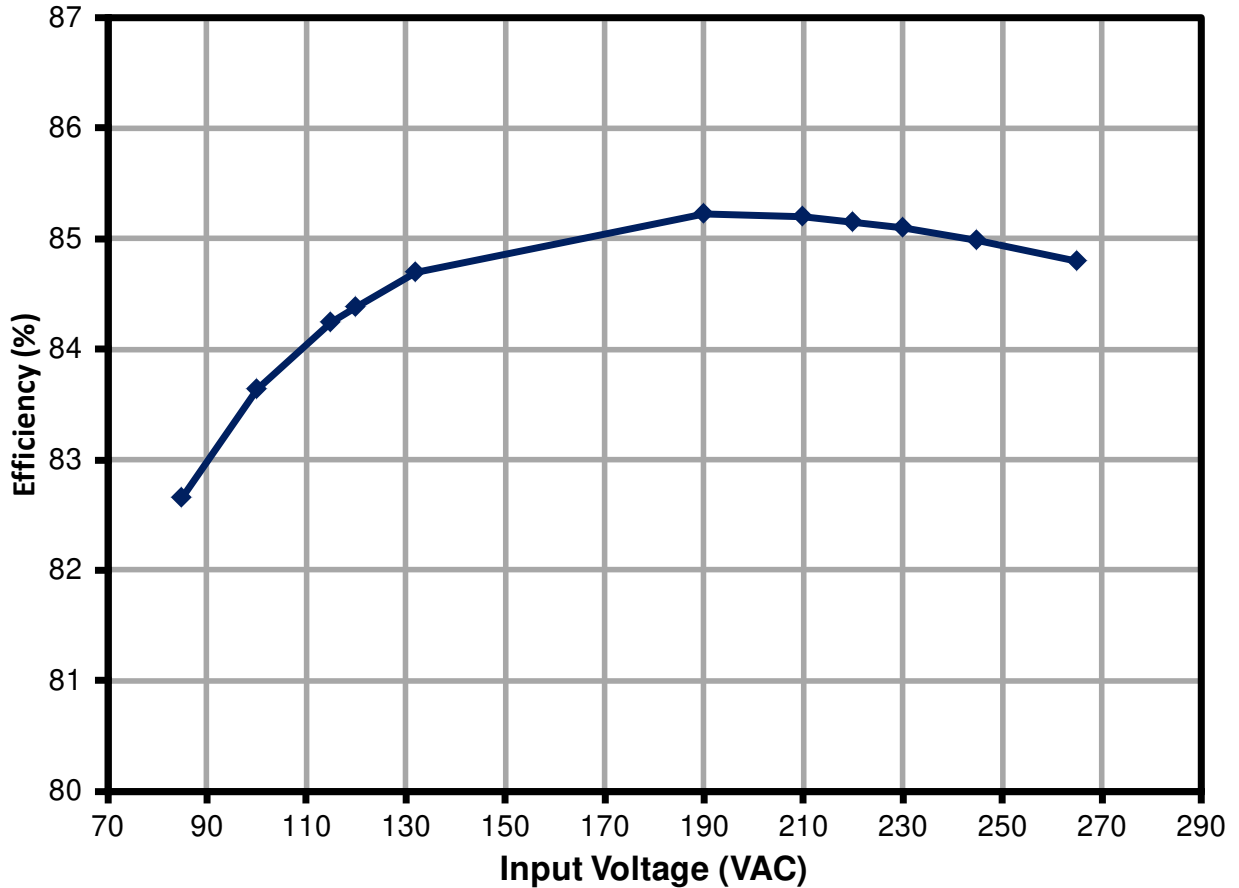


Figure 8 – Efficiency vs Line Voltage, Room Temperature

## 9.2 Active Mode Efficiency (at USB Socket) vs. Load

### 9.2.1 Efficiency without Schottky Diode in Parallel with Q1, SR FET

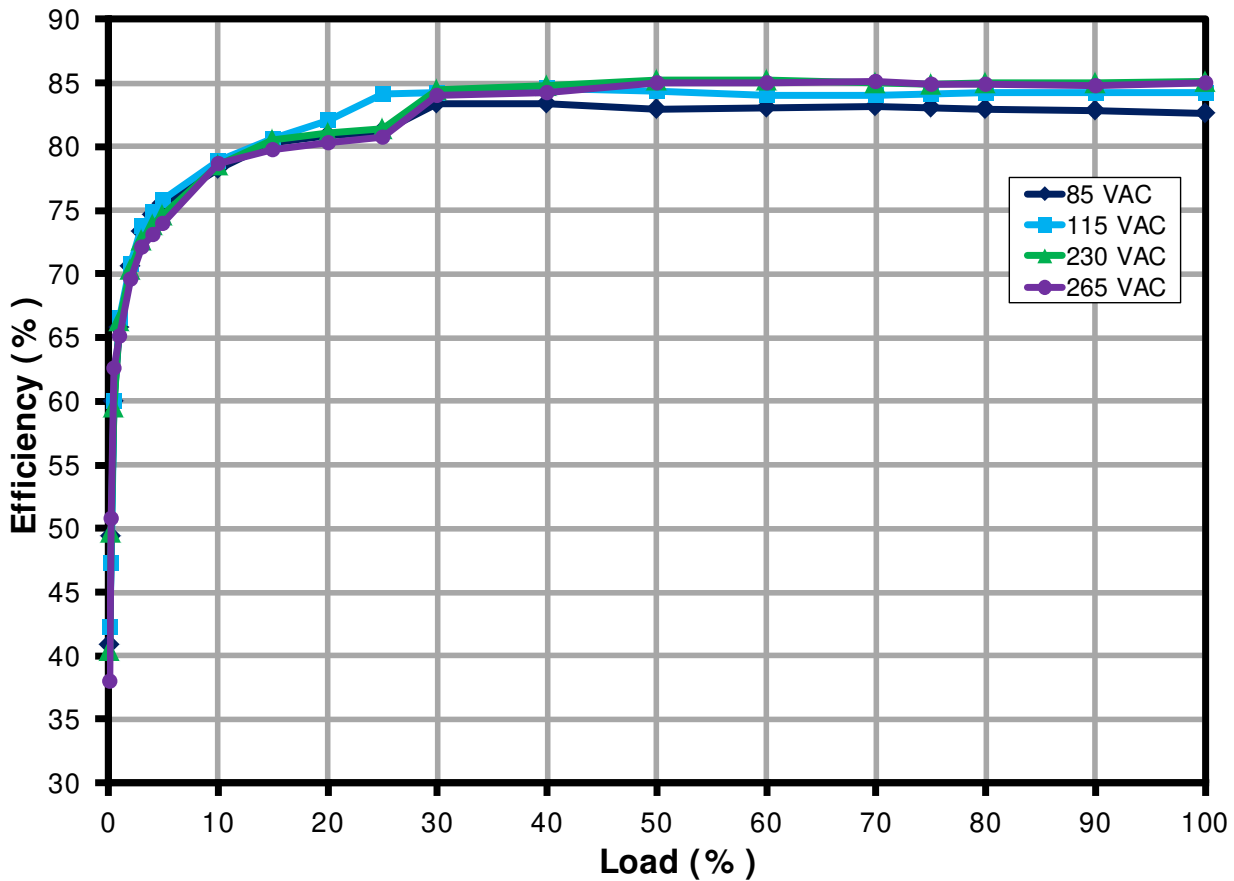


Figure 9 – Efficiency vs Load, Room Ambient

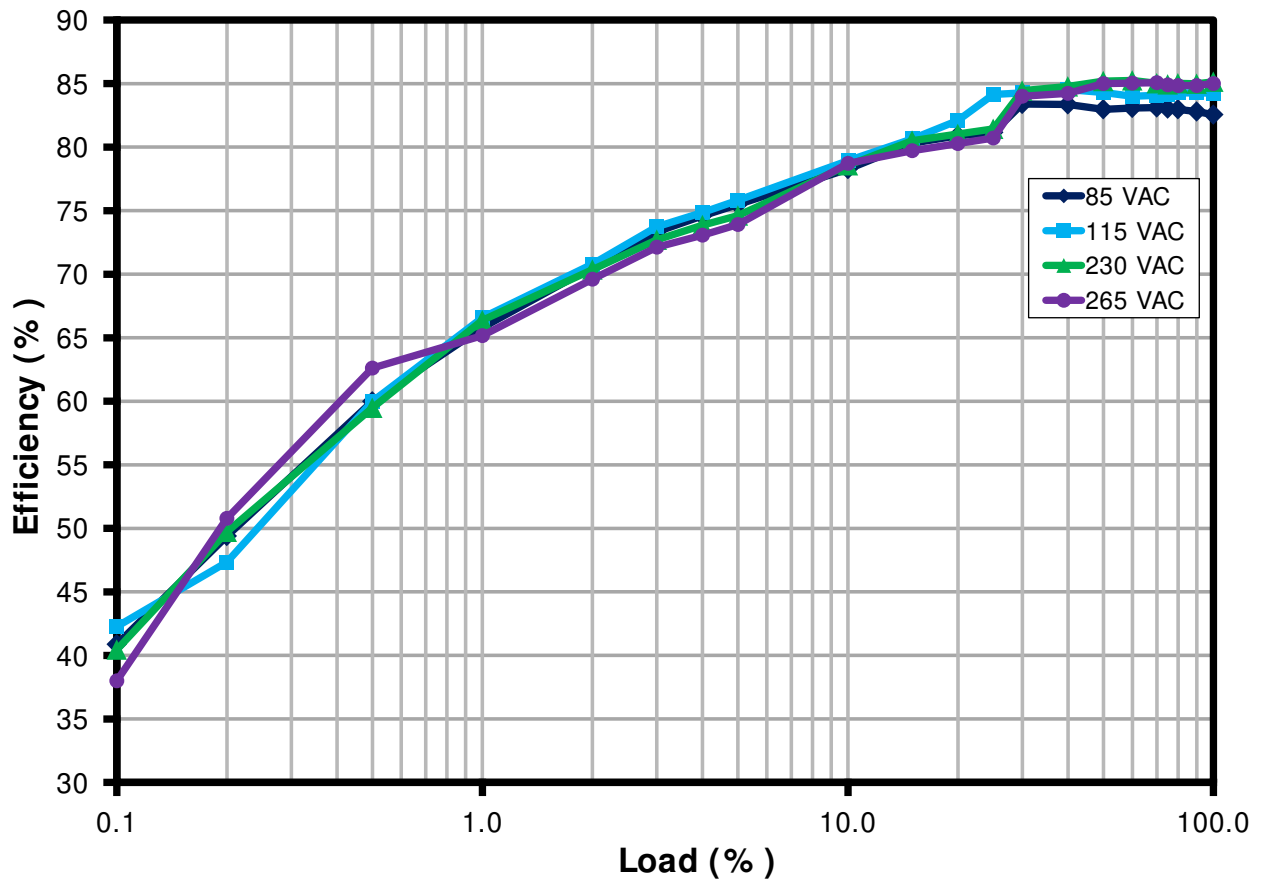


Figure 10 - Efficiency vs Load (log scale to demonstrate light load performance)





9.2.2 Efficiency with a Schottky Diode, SS16, in Parallel with Q1, SR FET

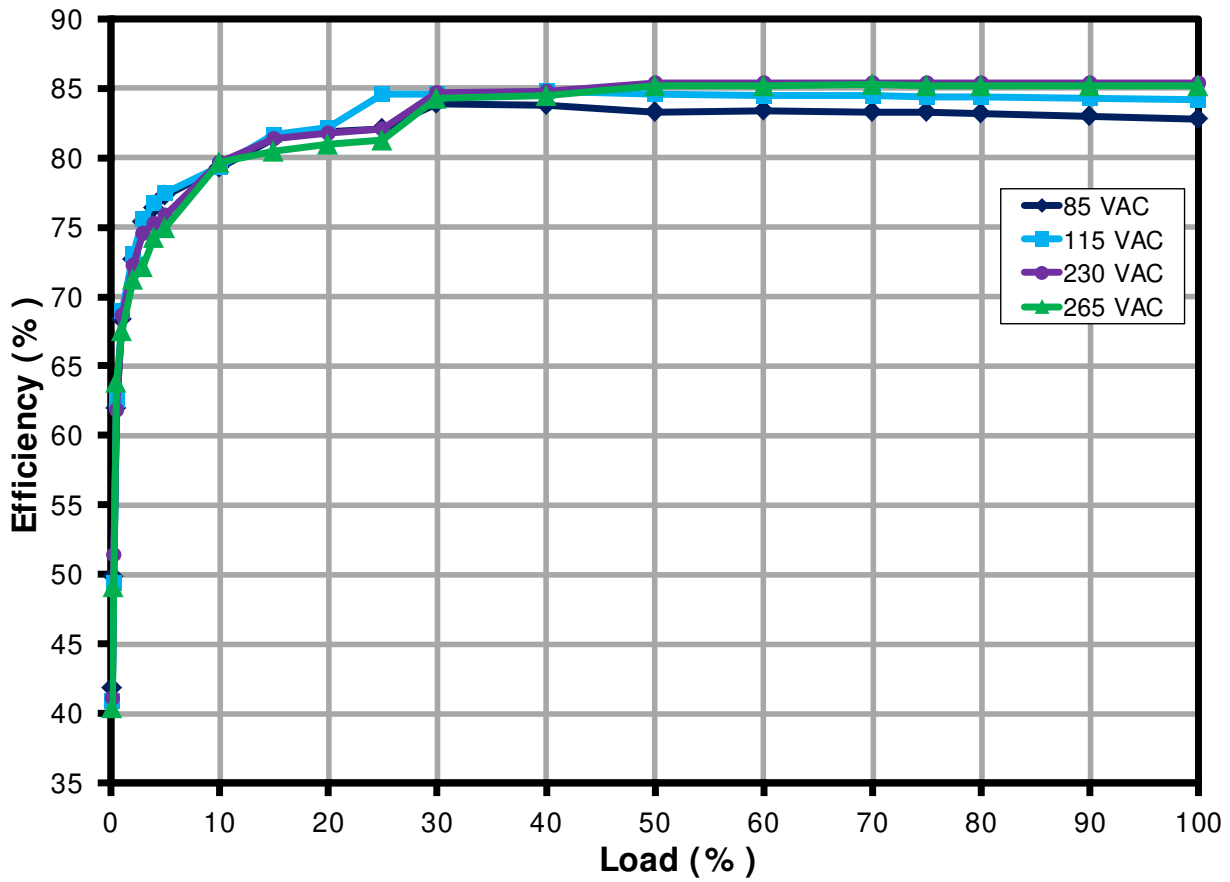


Figure 11 – Efficiency vs Load, Room Temperature, 60 Hz.

### 9.3 No-Load Input Power

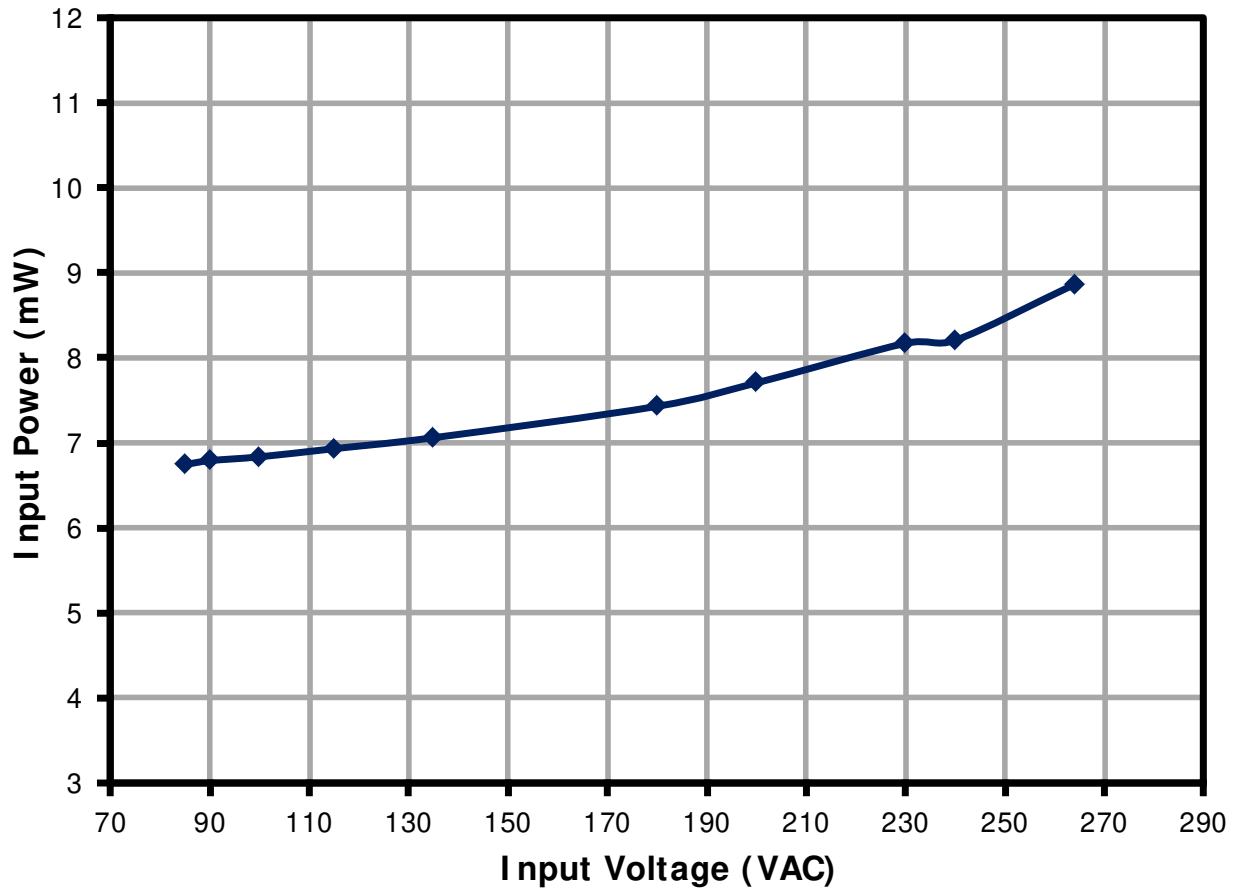


Figure 12 – No Load Input Power vs. Input Line Voltage, Room Temperature.

